

**Product / Package Information**

Package	LQFP
Body Size (mm)	14 X 14 X 1.4
Lead Count	128
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.13E-01	88.0	880000	61.78	617831
Thermosets	Epoxy & Phenol resin	Proprietary	5.40E-02	11.5	115000	8.07	80739
Other inorganic materials	Carbon black	1333-86-4	2.35E-03	0.5	5000	0.35	3510
Subtotal			4.69 E-01	100.00	1000000	70.21	702081

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.52E-01	97.50	975000	22.69	226912
Copper & its alloys	Iron	7439-89-6	3.65E-03	2.35	23500	0.55	5469
Copper & its alloys	Zinc	7440-66-6	1.87E-04	0.12	1200	0.03	279
Copper & its alloys	Phosphorus	7723-14-0	4.67E-05	0.03	300	0.01	70
Subtotal			1.56 E-01	100.00	1000000	23.27	232730

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	1.28 E-03	100.0	1000000	0.19	1915

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.13 E-03	100.0	1000000	0.92	9173

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	5.72E-03	99.00	990000	0.86	8563
Precious Metals	Palladium	7440-05-3	5.78E-05	1.00	10000	0.01	86
Subtotal			5.78 E-03	100.00	1000000	0.86	8650

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.62 E-02	100.0	1000000	3.93	39267

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.08E-03	73.54	735400	0.46	4611
Other organic materials	Epoxy resin A	TS ref# 10013	3.08E-04	7.35	73500	0.05	461
Others	Anhydride	TS ref# 10181	3.08E-04	7.35	73500	0.05	461
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.23E-04	2.94	29400	0.02	184
Other organic materials	Epoxy resin B	TS ref# 10237	1.23E-04	2.94	29400	0.02	184
Others	Epoxy resin modifier	TS ref# 10038	1.23E-04	2.94	29400	0.02	184
Others	Anhydride	TS ref# 10180	1.23E-04	2.94	29400	0.02	184
Subtotal	Subtotal		4.19 E-03	100.00	1000000	0.63	6270

Package Totals	Weight (g)	Percentage (%)	PPM
	6.68 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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